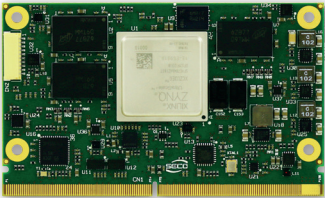




SOM-SMARC-ZU

SMARC® Rel. 2.0 compliant module with Zynq® Ultrascale+™ MPSoC

Flexible Arm® + FPGA Heterogeneous Processing in a Standard Form Factor



HIGHLIGHTS

CPU Zynq® Ultrascale+™ CG/EG/EV MPSoCs in C784 package	CONNECTIVITY PCI-e x4; 2x GbE; 2x CAN Bus; 2x SPI; 12x GPIOs
GRAPHICS Integrated Arm® Mali-400 MP2 GPU	MEMORY Up to 8GB + 2GB DDR4 soldered down

Available in Industrial Temperature Range



MAIN FIELDS OF APPLICATION

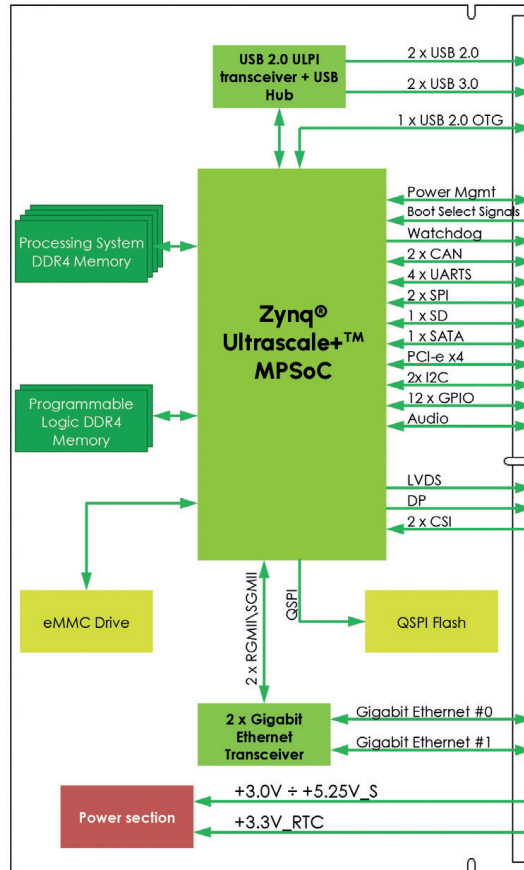


FEATURES

Processor	Zynq® Ultrascale+™ ZU2CG, ZU3CG, ZU4CG or ZU5CG MPSoCs: Dual-core Arm® Cortex®-A53 MPCore Application Processing Unit + Dual-core Arm® Cortex®-R5 Real-Time Processing Unit	USB	1x USB 2.0 OTG 2x USB 2.0 Host 2x USB 3.0 Host
	Zynq® Ultrascale+™ ZU2EG, ZU3EG, ZU4EG, ZU5EG, ZU4EV or ZU5EV MPSoCs: Quad-core Arm® Cortex®-A53 MPCore Application Processing Unit + Dual-core Arm® Cortex®-R5 Real-Time Processing Unit	PCI-e	PCI-e x4 interface
Memory	Soldered Down DDR4-2400 memory Up to 8GB for Processing System Unit + up to 2GB for Programmable Logic	Audio	Dependent on the IP implemented in the programmable logic
Graphics	Only on EG and EV MPSoCs: Integrated Arm® Mali-400 MP2 Graphics Processing Unit Multicore 2D/3D acceleration at 667MHz OpenGL ES 1.1 / 2.0, OpenVG 1.0 / 1.1 On EV MPSoCs only, H.264/H.265 integrated video codec	Serial Ports	2 x UART Tx/Rx/RTS/CTS 2 x UART Tx/Rx 2 x CAN Bus
Video Interfaces	18- / 24-bit Dual Channel LVDS interface DP interface 2 x CSI interfaces	Other Interfaces	2x I2C Bus 2 x SPI interfaces 12 x GPIOs Boot select signals Power Management Signals
Video Resolution	DP: Up to 4096 x 2160 LVDS: Dependent on the IP implemented in the programmable logic	Power Supply	+3V/+5.25V _{DC} +3.3V _{RTC}
Mass Storage	1 x external S-ATA Gen3 Channel SD interface QSPI Flash soldered-on-board Optional eMMC 4.51 drive soldered on-board	Operating System	Linux Android
Networking	Up to 2 x Gigabit Ethernet interfaces	Operating Temperature*	0°C ÷ +60°C (Commercial version) -40°C ÷ +85°C (Industrial version)
		Dimensions	50 x 82 mm (1.97" x 3.23")

*Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated.

BLOCK DIAGRAM



Streamline and expedite your edge computing implementations

EDGEHOG OS

A flexible operating system that adapts to your needs, thanks to the customization tool and Docker support. Reliability and security are built-in through a dual-partition system and native integration with Exein's robust AI-based protection.

DATA ORCHESTRATION

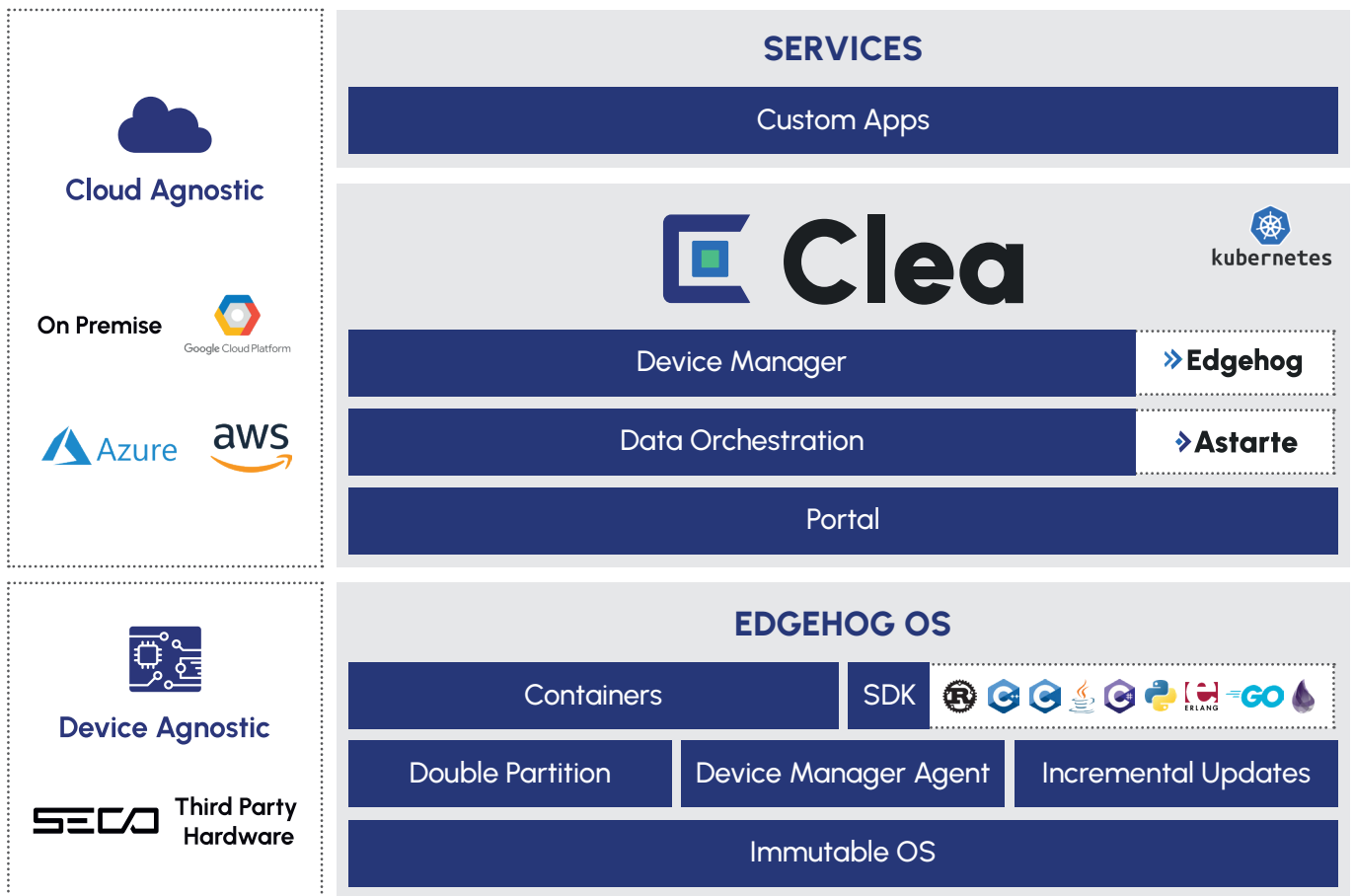
Integrate third-party services, simplify data flows and analysis, and enhance business efficiency by enabling easy and fast utilization of AI.

DEVICE MANAGER

Update, configure, and manage remote devices. Optimize time and costs to maximize operational efficiency and security without the need for costly field interventions.

PORTAL

Analyze data from remote devices, customize the user experience with applications tailored to user needs, and manage user rights, company access, and tenant privileges.



Scan to know more about our solution

EDGEHOG OS



CLEA DOCS

